Direct Attach Copper Cable Broad Market Potential

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- Richard Mellitz (Samtec)

Outline

- Relative market size of Direct Attach Copper Cables (DAC)
- Challenges with current network use-case
- Network deployment options for 100G serial
- Challenges with 100G serial in current switch design
- Options for 100G serial switch design

Relative market size of DAC

Typically 10x larger than equivalent optical market Interconnection Volume

- Four sections per colo & multiple colos (≥ 4) per data center
- Volumes below are per section (except DCR to Metro)

A End	Z End	Volume	Reach (max)	Medium	Cost Sensitivity	Market Space
Server ‡	TOR	10k – 100k	3 m	Copper	Extreme	
TOR	LEAF	1k – 10k	20 m	Fiber (AOC)	High	LAN
LEAF	SPINE	1k – 10k	400 m	SMF	High	
SPINE	DCR	100 - 1000	1,000 m	SMF	Medium	Campus
DCR	Metro	100 - 300	10 - 80 km	SMF	Low	WAN

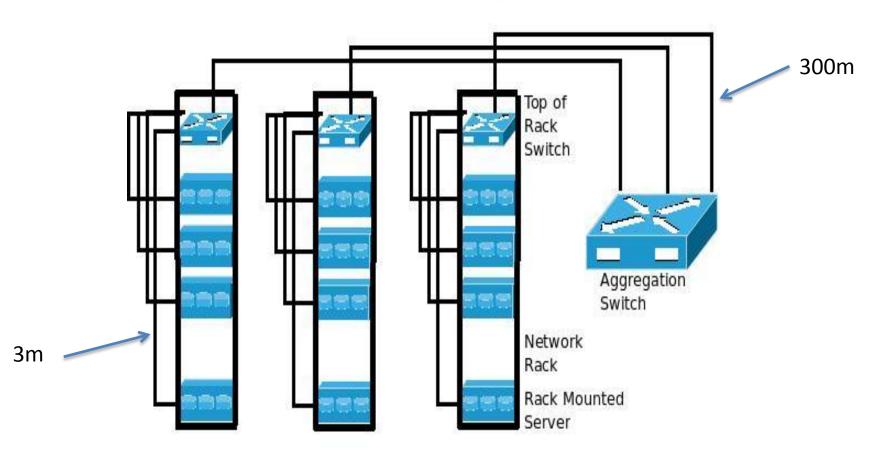
‡ Server-TOR links may be served by breakout cables

Source: Brad Booth, Microsoft http://www.ieee802.org/3/400GSG/public/13_11/booth_400_01a_1113.pdf

IEEE 802.3 400G Study Group - November 2013

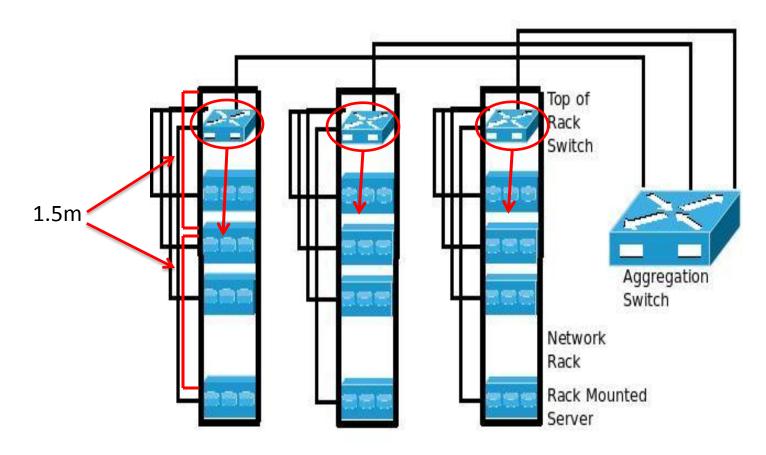
Current deployment use case has 3m DAC for TOR switch and 30-300m AOC for Aggregation switch

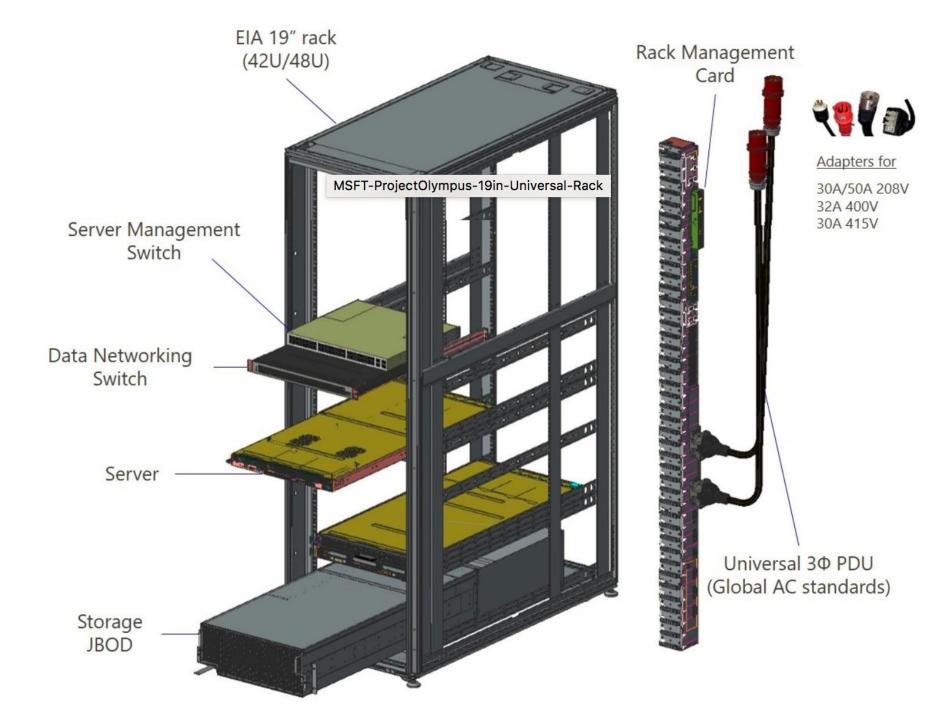
Top-Of-Rack (TOR) - Network Connectivity Architecture



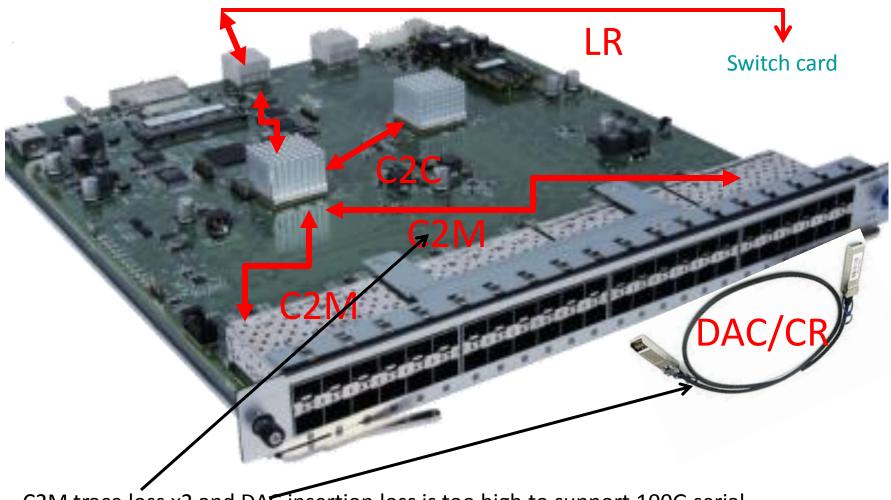
Improvement option 1: Move Switch to center of rack

Top-Of-Rack (TOR) - Network Connectivity Architecture





Challenges for 100G serial with current switch design



C2M trace loss x2 and DAC insertion loss is too high to support 100G serial

56Gbps PAM4 Channel Link Budget (ball to ball)

<u>Traditional</u> 56 Gbps, f₀=14 GHz

<u>Traditional</u> 112 Gbps, f₀=28 GHz

Parameter	Loss	
External 'raw' cable loss (3m)		
2 Host PCB trace 9" Megtron 6)	2 x 7.3 dB	
Connectors	2 x 1.2 dB	
2 Module PCB & capacitor	2 x 1.5 dB	
Total channel loss	29 dB	

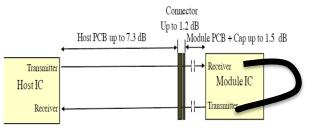
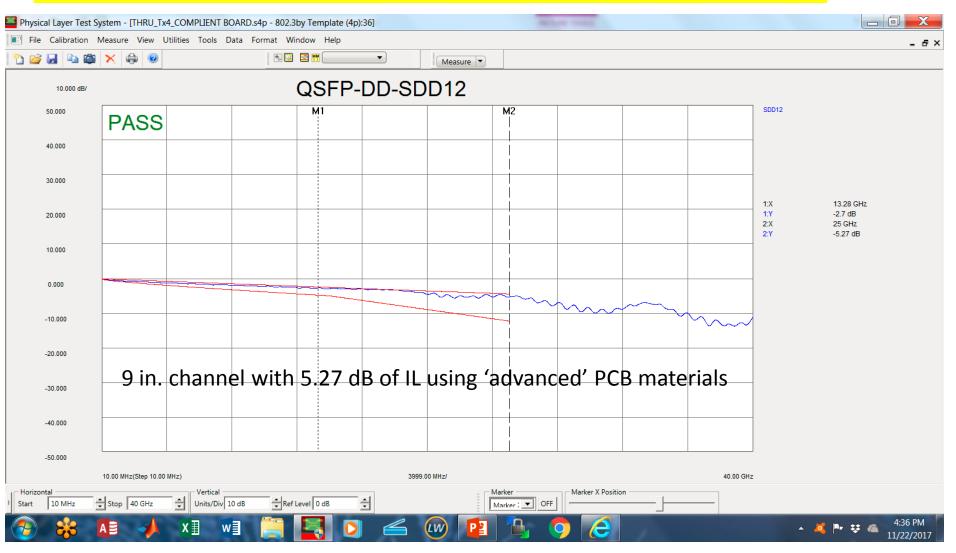


Figure 13-20. CEI-28G-VSR full Channel Reference Model

Improvement option 2: Low Loss PCB

Low loss switch channels can be achieved with 'advanced' PCB materials



See: diminico_100GEL_01_0118

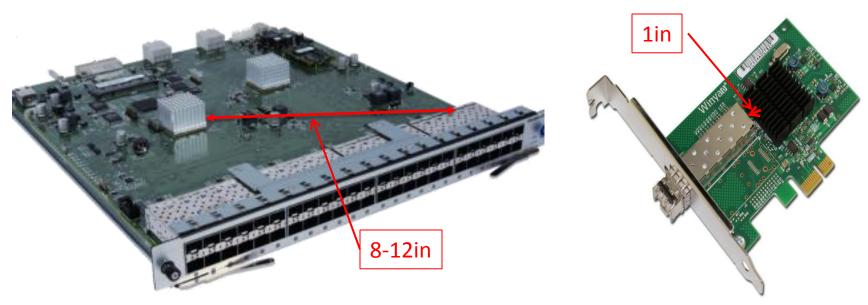
Improvement option 3: internal cables replace PCB traces

Key Benefits: > Lower System-Level Costs: > Eliminate the need for costly PCB materials (Nelco, Megtron, Tachyon, etc) > Eliminate the use of additional DF

- Eliminate the use of additional DFE or retimer chips to drive long traces
- Improved thermal performance with 1x1 cages (air-cooled)
- > Architectural Flexibility:
 - Freedom to locate ASIC anywhere (eg. further from backplane)
 - > Enable lower power ASIC
 - > Extended reach from ASIC to I/O
 - > Enable longer external copper I/O cables
 - > Cool the ports and the ASIC better
- > New ways to handle power integrity to large ASICs

Improvement option 4: Define asymmetric switch to server connections

Define end to end budgets that take advantage of short NIC traces



Switch ports require long host to module traces

Server ports have very short host to module traces

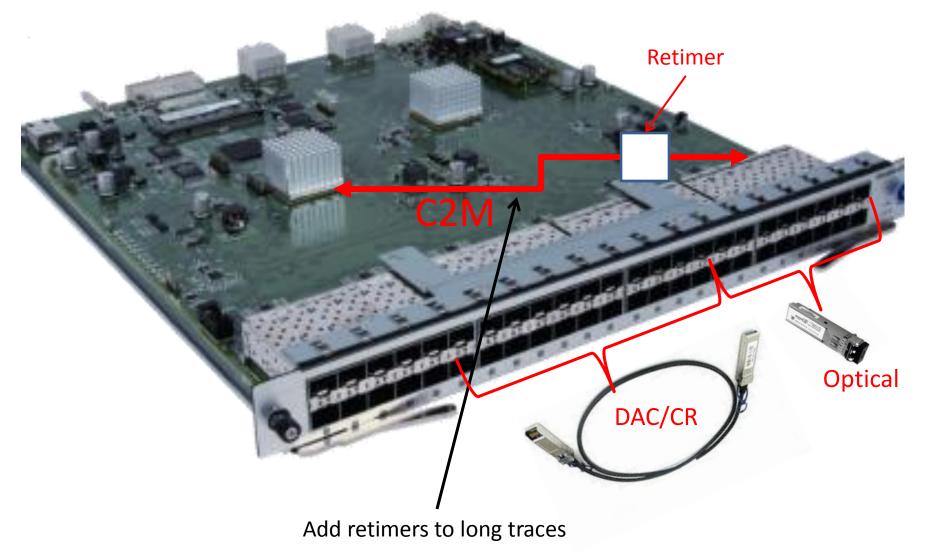
Improvement option 5: Switch chip to port optimization

Optical

DAC/CR

Short traces support DAC and optics, Long traces are optics only

Improvement option 6: Add retimers



Summary:

- DAC is not dead
 - Copper variants are prevalent and economically critical in the market today because of the cost/performance tradeoff they provide
 - Most cost effective intra rack connection
 - 10x larger market size vs optics
 - Multiple options exist to enable 100G serial DAC to provide the cost benefits demanded by end users